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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10070292	FILING DATE 03/05/2002	CLASS 427	SUBCLASS 301	GAU 1762	EXAMINER Bam
**APPLICANTS: Tanaka Hirokazu; Hirono Satoshi; Niino Hiroyuki; Yabe Akira;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/JP00/04491 07/06/2000					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials				204552022500	
TITLE : Method for preliminary treatment of material to be subjected to electroless plating					
U.S. DEPT. OF COMM./PAT. & TM-PTO-435L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	
		Print Claim for O.G.	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		PREPARED FOR ISSUE	
		Applicati n Examiner	
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